## Raise3D Pro3 HS Series Technical Specifications

The Raise3D Pro3 HS Series is a powerful professional-grade machine that builds upon the various performance improvements introduced on Raise3D's flagship Pro3 Series. It improves on printing speed, production efficiency and reliability. With Hyper FFF® technology, it offers high-speed printing for composite materials. The new auto filament switching function and supports 2.5kg filament spools, with the goal of bestowing general manufacturers and print farmers with the ability to produce small batches efficiently and reliably, whether they're end-use parts or tooling fixtures.

Printer	Raise3D Pro3 HS		Raise3D Pro3 Plus HS		
Build Volume (W × D × H)	Single Extruder Print	Dual Extruder Print	Single Extruder Print	Dual Extruder Print	
	300 × 300 × 300 mm (11.8 × 11.8 × 11.8 inch)	255 × 300 × 300 mm (10 × 11.8 × 11.8 inch)	300 × 300 × 605 mm (11.8 × 11.8 × 23.8 inch)	255 × 300 × 605 mm (10 × 11.8 × 23.8 inch)	
Machine Size (W × D × H)	620 × 626 × 760 mm (24	4.4 × 24.6 × 29.9 inch) 620 × 626 × 1105 mm (24.4 × 24.6 × 43.5 inch)			
Weight -	Net Weight	Gross Weight (Carton with Pallet)	Net Weight	Gross Weight (Carton with Palle	
	54 kg (119 lbs)	75.7 kg (166.9 lbs)	64 kg (141 lbs)	88.7 kg (195.5 lbs)	
General	Print Technolo Print Head Syste Filament Diame XYZ Step S Standard Printing Spe Build Plate Leveli Heated Bed Mate Heated Bed Max Temperatu Nozzle Diame Max Nozzle Temperatu Layer Heig Automatic Filament Switchi RFID Sens Filament Run-Out Sens Filament Run-Out Sens Filament Run-Out Sens Filament Run-Out Sens Filament Run-Out Sens Storage Temperatu	<ul> <li>Dual-head with Electronic</li> <li>1.75 mm</li> <li>0.78125, 0.78125, 0.0781</li> <li>300 mm/s</li> <li>Flexible Steel Plate with E</li> <li>Mesh-leveling with Flatner</li> <li>silicone</li> <li>120°C</li> <li>0.4 mm (Default), 0.2/ 0.6</li> <li>320°C</li> <li>The Pro3 HS Series is cor</li> <li>the layer height can vary</li> <li>To achieve stable print re</li> <li>a layer height between 0</li> <li>Available (Coming Soon)</li> <li>Available (Coming Soon)</li> <li>Available</li> <li>ter HEPA Filter with Activated</li> <li>Available</li> <li>wi-Fi, LAN, USB port, Live</li> <li>55 dB (A) When Buildin</li> <li>15-30°C, 10-90% RH, non</li> </ul>	0.78125, 0.78125, 0.078125 micron 300 mm/s Flexible Steel Plate with BuildTak Mesh-leveling with Flatness Detection Silicone 120°C 0.4 mm (Default), 0.2/ 0.6/ 0.8/ 1.0 mm (Available) 320°C The Pro3 HS Series is compatible with 0.2, 0.4, 0.6, 0.8 and 1.0 mm nozzles, and the layer height can vary between 0.05-0.6 mm. To achieve stable print results, when using 0.4 mm nozzles, we recommend using a layer height between 0.1-0.3 mm. Available (Coming Soon) Available (Coming Soon) Available HEPA Filter with Activated Charcoal		
Electrical	Power Supply In Power Supply Out		100-240 V AC, 50/ 60 Hz 230 V @ 3.3 A 24 V DC, 600 W		
Material	Material Ty Third Party Mate	Hyper Speed: PLA/ ABS Industrial: PPA CF/ PPA G Premium: PLA/ ABS/ ASA	Hyper Core: PPA CF/ PPA GF/ ABS CF Hyper Speed: PLA/ ABS Industrial: PPA CF/ PPA GF/ PET CF/ PET GF/ PETG ESD/ PET Support/ PPA Support Premium: PLA/ ABS/ ASA/ PETG/ PC/ TPU-95A/ PVA+ Supported by Raise3D OFP (Open Filament Program)*		
Software	Slicing Softwa Supported File Typ Supported ( Machine Code Ty	oes STL/ OBJ/ 3MF/ OLTP/ STI DS Windows/ macOS/ Linux	STL/ OBJ/ 3MF/ OLTP/ STEP/ STP/ IGES/ IGS Windows/ macOS/ Linux		
Printer Controller		ork Wi-Fi, Ethernet Available on 1024 × 600 Iler Atmel ARM Cortex-M4 12 Iler NXP ARM Cortex-A9 Quar ory 1 GB	Wi-Fi, Ethernet Available 1024 × 600 Atmel ARM Cortex-M4 120 MHz FPU NXP ARM Cortex-A9 Quad 1 GHz 1 GB 16 GB Embedded Linux		

\*For detailed information and slicing profiles of the materials supported by Raise3D OFP, please visit https://www.ideamaker.io/.